

Electronic Patent Application Fee Transmittal

Application Number:	10719218			
Filing Date:	20-Nov-2003			
Title of Invention:	STRUCTURE, MATERIAL, AND DESIGN FOR ASSEMBLING A LOW-K SI DIE TO ACHIEVE AN INDUSTRIAL GRADE RELIABILITY WIRE BONDING PACKAGE			
First Named Inventor/Applicant Name:	Wen-Chou Vincent Wang			
Filer:	CINDY H. SHU/Valerie Olsen			
Attorney Docket Number:	ALTRP100/A1198			

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
-------------	----------	----------	--------	----------------------

Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1440	1440
------------------------	------	---	------	------

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1446